

Product/process change notification

PCN213301

Dear

Please find attached our Infineon Technologies AG PCN:

Introduction of an additional assembly production at UTAC Thai Ltd (UTL2), Chachoengsao, Thailand for Select 8-Lead TSSOP package

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **01 Oct 2021**
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Notwithstanding the aforesaid individual agreements shall prevail

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.

For further details, please visit our website:

<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

► **Products affected:**

Please refer to attached affected product list [12]

► **Detailed change information:**

Subject: Introduction of an additional assembly production at UTAC Thai Ltd (UTL2), Chachoengsao, Thailand for Select 8-Lead TSSOP package

Reason: Expansion of assembly production to assure continuity of supply and enable flexible manufacturing.

Description:

<u>Old</u>	<u>New</u>
<ul style="list-style-type: none"> ■ Orient Semiconductor Electronics, Kaohsiung, Taiwan and ■ AMKOR Technology Philippines Inc. (ATP), Muntinlupa City, Philippines 	<ul style="list-style-type: none"> ■ Orient Semiconductor Electronics, Kaohsiung, Taiwan and ■ AMKOR Technology Philippines Inc. (ATP), Muntinlupa City, Philippines and ■ UTAC Thai Ltd (UTL2) Chachoengsao, Thailand
<ul style="list-style-type: none"> ■ MOQ Unit Per Tube Qty: 162 units 	<ul style="list-style-type: none"> ■ MOQ Unit Per Tube Qty: 158 units

<u>Old BOM</u>	<u>New BOM</u>																																																
<ul style="list-style-type: none"> ■ OSE (Au) <table border="1"> <tr><td>Mold Compound</td><td>CEL-9200HF</td></tr> <tr><td>Leadframe</td><td>Cu LeadFrame</td></tr> <tr><td>Die Attach</td><td>8340</td></tr> <tr><td>Bond Wire</td><td>25 microns Au</td></tr> </table> ■ OSE (Cu) <table border="1"> <tr><td>Mold Compound</td><td>G631</td></tr> <tr><td>Leadframe</td><td>Cu LeadFrame</td></tr> <tr><td>Die Attach</td><td>CRM1076</td></tr> <tr><td>Bond Wire</td><td>20 microns Cu based</td></tr> </table> ■ AMKOR <table border="1"> <tr><td>Mold Compound</td><td>G700</td></tr> <tr><td>Leadframe</td><td>Cu LeadFrame</td></tr> <tr><td>Die Attach</td><td>8290</td></tr> <tr><td>Bond Wire</td><td>20 microns Cu based</td></tr> </table> 	Mold Compound	CEL-9200HF	Leadframe	Cu LeadFrame	Die Attach	8340	Bond Wire	25 microns Au	Mold Compound	G631	Leadframe	Cu LeadFrame	Die Attach	CRM1076	Bond Wire	20 microns Cu based	Mold Compound	G700	Leadframe	Cu LeadFrame	Die Attach	8290	Bond Wire	20 microns Cu based	<ul style="list-style-type: none"> ■ OSE (Au) <table border="1"> <tr><td>Mold Compound</td><td>CEL-9200HF</td></tr> <tr><td>Leadframe</td><td>Cu LeadFrame</td></tr> <tr><td>Die Attach</td><td>8340</td></tr> <tr><td>Bond Wire</td><td>25 microns Au</td></tr> </table> ■ OSE (Cu) <table border="1"> <tr><td>Mold Compound</td><td>G631</td></tr> <tr><td>Leadframe</td><td>Cu LeadFrame</td></tr> <tr><td>Die Attach</td><td>CRM1076</td></tr> <tr><td>Bond Wire</td><td>20 microns Cu based</td></tr> </table> ■ AMKOR <table border="1"> <tr><td>Mold Compound</td><td>G700</td></tr> <tr><td>Leadframe</td><td>Cu LeadFrame</td></tr> <tr><td>Die Attach</td><td>8290</td></tr> <tr><td>Bond Wire</td><td>20 microns Cu based</td></tr> </table> 	Mold Compound	CEL-9200HF	Leadframe	Cu LeadFrame	Die Attach	8340	Bond Wire	25 microns Au	Mold Compound	G631	Leadframe	Cu LeadFrame	Die Attach	CRM1076	Bond Wire	20 microns Cu based	Mold Compound	G700	Leadframe	Cu LeadFrame	Die Attach	8290	Bond Wire	20 microns Cu based
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■ UTL2	
Mold Compound	G600
Leadframe	Cu LeadFrame
Die Attach	8200T
Bond Wire	20 microns Cu based

▶ **Product identification:** Traceability of product to assembly site through the date code marked on the package.

▶ **Impact of change:** Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No change in fit and form (except reduction of e.g. wire diameter; if applicable).

▶ **Attachments:** Affected product list [12]
Supporting documents

▶ **Time schedule:**

■ Final qualification report:	Available
■ First samples available:	on request
■ Intended start of delivery:	2021-11-30

If you have any questions, please do not hesitate to contact your local sales office.

[Product Change Notification] N° [PCN213301]

Introduction of an Additional Assembly Production at UTAC Thai Ltd (UTL2), Chachoengsao, Thailand
for Select 8-Lead TSSOP Package



Item	Marketing Part Number	Family	Sample Order Part Number	Sample Availability
1	CY2304NZZXC-1	CLOCKS	CY2304NZZXC-1KU	Available
2	CY2304NZZXC-1T	CLOCKS	CY2304NZZXC-1KU	Available
3	CY2304NZZXI-1	CLOCKS	CY2304NZZXI-1KU	Available
4	CY2304NZZXI-1T	CLOCKS	CY2304NZZXI-1KU	Available
5	CY25100KZXC46	CLOCKS	CY25100KZXC46KU	Subject to lead time
6	CY25100KZXC46T	CLOCKS	CY25100KZXC46KU	Subject to lead time
7	CY25100ZXCFC	CLOCKS	CY25100ZXCFCU	Subject to lead time
8	CY25100ZXCFT	CLOCKS	CY25100ZXCFCU	Subject to lead time
9	CY25100ZXIF	CLOCKS	CY25100ZXIFU	Subject to lead time
10	CY25100ZXIFT	CLOCKS	CY25100ZXIFU	Subject to lead time
11	CG7877AA	CLOCKS	CG7877WA	Subject to lead time
12	CG7877AAT	CLOCKS	CG7877WA	Subject to lead time